

**N-Ch MOSFET** 

#### **General Description**

The WSD75100DN56 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSD75100DN56 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

#### Features

- Reliable and Rugged
- Lead Free and Green Devices Available
- (RoHS Compliant)

## Product Summery

BV <sub>DSS</sub>		Ι <sub>D</sub>
75V	5.3mΩ	100A

## Applications

- DC-DC converter switching for Networkong
- General purpose switching

## **DFN5X6-8** Pin Configuration



## Absolute Maximum Ratings (T<sub>A</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	75	V
V <sub>GS</sub>	Gate-Source Voltage	±25	V
TJ	Maximum Junction Temperature	150	°C
I <sub>D</sub>	Storage Temperature Range	-55 to 150	°C
Is	Diode Continuous Forward Current,Tc=25°C	50	A
1	Continuous Drain Current, V <sub>GS</sub> =10V,T <sub>C</sub> =25°C	100	A
I <sub>D</sub>	Continuous Drain Current, V <sub>GS</sub> =10V,T <sub>C</sub> =100°C	73	A
I <sub>DM</sub>	Pulsed Drain Current ,T <sub>C</sub> =25°C	400	A
P	Maximum Power Dissipation,T <sub>C</sub> =25°C	155	W
PD	Maximum Power Dissipation,T <sub>C</sub> =100°C	62	W
D	Thermal Resistance-Junction to Ambient ,t =10s`	20	°C
$R_{\theta JA}$	Thermal Resistance-Junction to Ambient ,Steady State	60	°C
$R_{ ext{ heta}JC}$	Thermal Resistance-Junction to Case	0.8	°C
I <sub>AS</sub>	Avalanche Current, Single pulse,L=0.5mH	30	A
E <sub>AS</sub>	Avalanche Energy, Single pulse,L=0.5mH	225	mJ



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## Electrical Characteristics (T<sub>J</sub>=25 $^{\circ}$ C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	75			V	
$\triangle BV_{DSS} / \triangle T_J$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25 $^\circ\!\mathrm{C}$ , I_D=1mA		0.043		V/℃	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =25A		5.3	6.4	mΩ	
V <sub>GS(th)</sub>	Gate Threshold Voltage	—	2.0	3.0	4.0	V	
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient			-6.94		mV/℃	
IDSS	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}48V$ , $V_{\text{GS}}\text{=}0V$ , $T_{\text{J}}\text{=}25^\circ\!\mathrm{C}$			2	- uA	
IDSS	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}48V$ , $V_{\text{GS}}\text{=}0V$ , $T_{\text{J}}\text{=}55^\circ\!\mathrm{C}$			10		
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm20V$ , $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		50		S	
Rg	Gate Resistance	$V_{DS}$ =0V , $V_{GS}$ =0V , f=1MHz		1.0	2	Ω	
Qg	Total Gate Charge (10V)			65	85		
Q <sub>gs</sub>	Gate-Source Charge	$V_{DS}$ =20V , $V_{GS}$ =10V , $I_{D}$ =40A		20		nC	
$Q_{gd}$	Gate-Drain Charge			17			
T <sub>d(on)</sub>	Turn-On Delay Time			27	49		
Tr	Rise Time	$V_{DD}$ =30V , $V_{GEN}$ =10V , $R_{G}$ =1 $\Omega$ ,		14	26	ns	
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =1A ,RL=15Ω.		60	108	115	
T <sub>f</sub>	Fall Time			37	67		
Ciss	Input Capacitance			3500			
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =20V , V <sub>GS</sub> =0V , f=1MHz		395		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			195			

#### **Guaranteed Avalanche Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	V <sub>DD</sub> =25V , L=0.5mH , I <sub>AS</sub> =30A	198			mJ

#### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			50	А
I <sub>SM</sub>	Pulsed Source Current <sup>2,6</sup>	V <sub>G</sub> -V <sub>D</sub> -UV, Force Current			100	А
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =20A , TJ=25℃			1.4	V

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec .

2.The data tested by pulsed , pulse width  $\,\leq\,$  300us , duty cycle  $\,\leq\,$  2%

3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.5mH,  $I_{AS}$ =30A

4.The power dissipation is limited by 150  $^\circ\!\mathrm{C}$  junction temperature

5.The Min. value is 100% EAS tested guarantee.

6. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

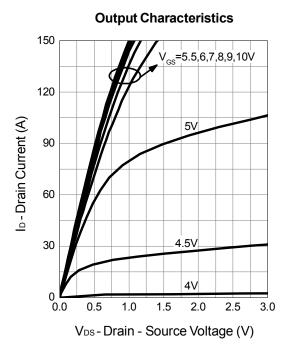
7.Package limitation current is 100A.



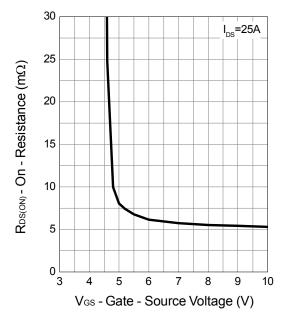
WSD75100DN56

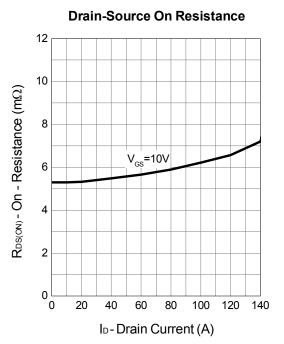
**N-Ch MOSFET** 

## **Typical Characteristics**

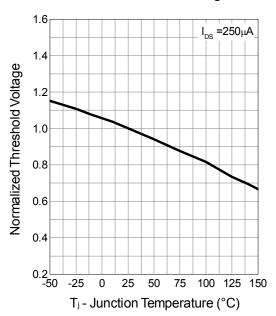


**Gate-Source On Resistance** 





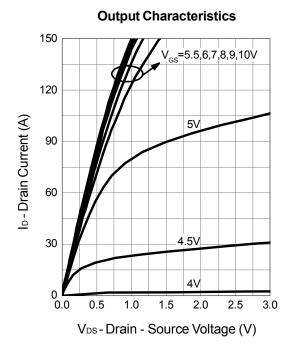
Gate Threshold Voltage





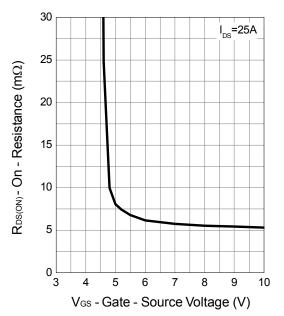
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**N-Ch MOSFET** 

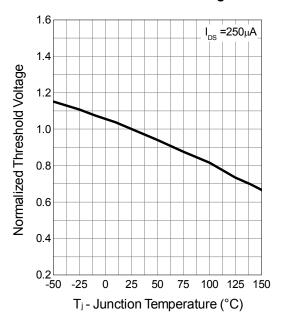


**Drain-Source On Resistance** 12 10 RDS(ON) - ON - Resistance (mΩ) 8 V<sub>GS</sub>=10V 6 4 2 0 L 0 100 20 40 60 80 120 140 ID-Drain Current (A)

**Gate-Source On Resistance** 



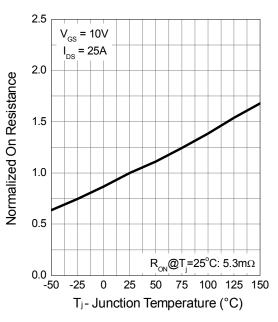
Gate Threshold Voltage



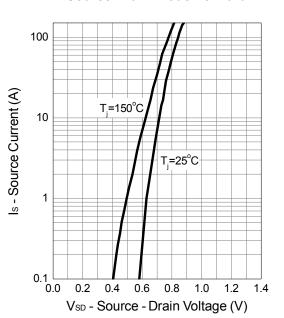


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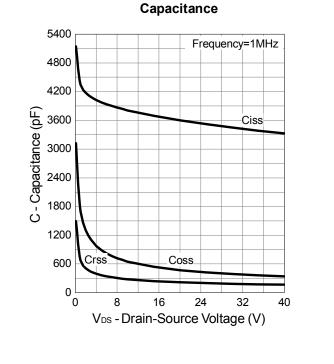
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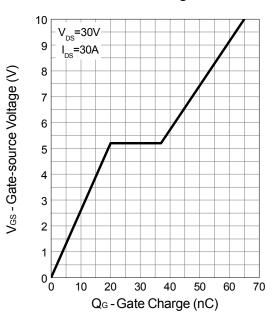
Drain-Source On Resistance



Source-Drain Diode Forward



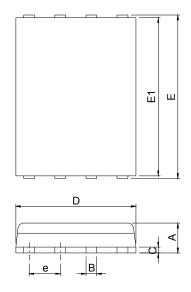
**Gate Charge** 

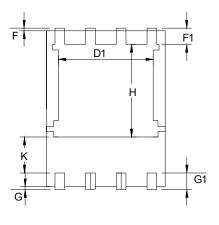




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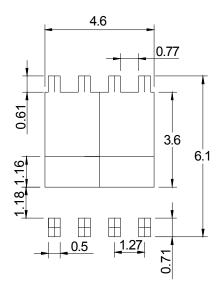
# Package Information DFN5x6-8





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SY MBOL	MILLIMETERS		INCHES			
6	MIN.	MAX.	MIN.	MAX.		
А	0.90	1.20	0.035	0.047		
В	0.3	0.51	0.012	0.020		
С	0.19	0.25	0.007	0.010		
D	4.80	5.30	0.189	0.209		
D1	4.00	4.40	0.157	0.173		
E	5.90	6.20	0.232	0.244		
E1	5.50	5.80	0.217	0.228		
е	1.27 BSC		0.050 BSC			
F	0.05	0.30	0.002	0.012		
F1	0.35	0.75	0.014	0.030		
G	0.05	0.30	0.002	0.012		
G1	0.35	0.75	0.014	0.030		
Н	3.34	3.9	0.131	0.154		
к	0.762	-	0.03	-		

RECOMMENDED LAND PATTERN



UNIT: mm

Note : 1.Dimension D, D1,D2 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 10 mil.



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